



**NOTE1:**  
 1) if the U1 flash had 4 chips select in one flash, R3, R4, R5 should be added and R10 should be removed.  
 2) else if the U1 flash is NAND double die FLASH, R3 should be added and R4, R5, R10 should be removed.  
 3) else if the U1 flash is HY27U50B611A, K9K2800, M29F0128 or the FLASH is made in TOSHIBA or SANDISK, single die, R10 should be added and R3, R4, R5 removed.  
 4) else the U1 flash is NAND or AG-AND single die FLASH, R10, R3, R4, R5 should be removed.

**NOTE2:**  
 This application supported:  
 1) one pcs of 4 chips select SLC and MLC in one flash  
 2) or one pcs of 2 chips select SLC and MLC in one flash  
 3) or one pcs of 1 chips select SLC and MLC in one flash  
 4) 8bit flash  
 5) NAND single, double die and quad die flash  
 6) or AG-AND single die and double die flash  
 7) had write protect switch

**NOTE3:**  
 if don't consider ESD, the FB2 should be shorted and R11 should be removed, otherwise all of them should be added.

Title		
leadwin technology (HK) co., Ltd.		
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